

Yuanming Chen

List of Publications by Year in descending order

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52
papers

888
citations

567281

15
h-index

526287

27
g-index

52
all docs

52
docs citations

52
times ranked

665
citing authors

#	ARTICLE	IF	CITATIONS
1	Additive-assisted cobalt electrodeposition as surface magnetic coating to enhance the inductance of spiral copper inductors. <i>Surfaces and Interfaces</i> , 2022, 28, 101603.	3.0	2
2	PET Surface Modification with Inkjet-Printing Pd ²⁺ /Epoxy Resin Solution for Selective Electroless Copper Plating. <i>ACS Applied Electronic Materials</i> , 2022, 4, 149-157.	4.3	7
3	Effect of 3-mercapto-1-propane sulfonate sulfonic acid and polyvinylpyrrolidone on the growth of cobalt pillar by electrodeposition. <i>Nanotechnology Reviews</i> , 2022, 11, 1209-1218.	5.8	5
4	Direct additive copper plating on polyimide surface with silver ammonia via plasma modification. <i>Applied Surface Science</i> , 2022, 587, 152848.	6.1	7
5	Enhancing peel strength between liquid crystal polymer and copper with plasma treatment, surface oxidation, and silane coating. <i>Journal of Applied Polymer Science</i> , 2022, 139, .	2.6	1
6	Polymer-based Cu/Ag composite as seed layer on insulating substrate for copper addition of multi-dimensional conductive patterns. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2021, 123, 254-260.	5.3	3
7	Investigation on Cu-Sn intermetallic compounds growth and signal transmission loss of the diverse copper lines after soldering in printed circuit board. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 22372-22386.	2.2	3
8	A modified model of conductor roughness for manufacturing copper lines of printedcircuit board. <i>Circuit World</i> , 2021, ahead-of-print, .	0.9	1
9	Label-free diagnosis for colorectal cancer through coffee ring-assisted surface-enhanced Raman spectroscopy on blood serum. <i>Journal of Biophotonics</i> , 2020, 13, e201960176.	2.3	52
10	In-situ chemical polymerization of Cu-Polythiophenes composite film as seed layer for direct electroplating on insulating substrate. <i>Electrochimica Acta</i> , 2020, 330, 135358.	5.2	6
11	Hydroquinone oriented growth control to achieve high-quality copper coating at high rate for electronics interconnection. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2020, 112, 130-136.	5.3	10
12	Surface coarsening of carbon fiber/cyanate ester composite for adhesion improvement of electroless copper plating as conductive patterns. <i>Materials Chemistry and Physics</i> , 2020, 255, 123597.	4.0	9
13	Investigation of polyvinylpyrrolidone as an inhibitor for trench super-filling of cobalt electrodeposition. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2020, 112, 232-239.	5.3	13
14	Process, fundamental and application of one-step molten-salt synthesized BaTi2O5 nanorods. <i>Journal of Alloys and Compounds</i> , 2020, 826, 154064.	5.5	5
15	Metal oxide alternatives for efficient electron transport in perovskite solar cells: beyond TiO ₂ and SnO ₂ . <i>Journal of Materials Chemistry A</i> , 2020, 8, 19768-19787.	10.3	60
16	Copolymer of Pyrrole and 1,4-Butanediol Diglycidyl as an Efficient Additive Leveler for Through-Hole Copper Electroplating. <i>ACS Omega</i> , 2020, 5, 4868-4874.	3.5	37
17	Whisker inhibited Sn-Bi alloy coating on copper surface to increase copper bonding strength for signal loss reduction of PCB in high-frequency. <i>Applied Surface Science</i> , 2020, 513, 145718.	6.1	12
18	Temperature-dependent inhibition of PEG in acid copper plating: Theoretical analysis and experiment evidence. <i>Materials Today Communications</i> , 2020, 24, 100973.	1.9	13

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19	Cyanide-free silver immersion deposition involving 3-mercapto-1-propanesulfonic acid for copper finishing. <i>Materials Chemistry and Physics</i> , 2020, 244, 122671.	4.0	9
20	Optoplasmonic Hybrid Materials for Trace Detection of Methamphetamine in Biological Fluids through SERS. <i>ACS Applied Materials & Interfaces</i> , 2020, 12, 24192-24200.	8.0	43
21	Anisotropic growth of electroless nickel-phosphorus plating on fine sliver lines for L-shape terminal electrode structure of chip inductor. <i>Applied Surface Science</i> , 2019, 496, 143633.	6.1	2
22	A novel structured spiral planar embedded inductor: Electroless-plating NiCoP alloy on copper coil as magnetic core. <i>Journal of Magnetism and Magnetic Materials</i> , 2019, 489, 165363.	2.3	5
23	Communication "Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. <i>Journal of the Electrochemical Society</i> , 2019, 166, D467-D469.	2.9	3
24	Compatible Ag ⁺ Complex-Assisted Ultrafine Copper Pattern Deposition on Poly(ethylene) Terephthalate (PET) Substrate. <i>ACS Applied Materials & Interfaces</i> , 2019, 11, 44811-44819.	8.0	36
25	Effect of surface finishing on signal transmission loss of microstrip copper lines for high-speed PCB. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 16226-16233.	2.2	11
26	Air-plasma surface modification of epoxy resin substrate to improve electroless copper plating of printed circuit board. <i>Vacuum</i> , 2019, 170, 108967.	3.5	16
27	Solvent-dependent ultrasonic surface treatment on morphological reconstruction of CuO particles for copper electrodeposition. <i>Applied Surface Science</i> , 2019, 491, 206-215.	6.1	17
28	Nickel-nanoparticles-assisted direct copper-electroplating on polythiophene conductive polymers for PCB dielectric holes. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2019, 100, 262-268.	5.3	13
29	Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. <i>Journal of the Electrochemical Society</i> , 2019, 166, D93-D98.	2.9	14
30	Numerical simulation and experiments to improve throwing power for practical PCB through-holes plating. <i>Circuit World</i> , 2019, 45, 221-230.	0.9	9
31	Enhancing adhesion performance of sputtering Ti/Cu film on pretreated composite prepreg for stacking structure of IC substrates. <i>Composites Part B: Engineering</i> , 2019, 158, 400-405.	12.0	27
32	Computational analysis and experimental evidence of two typical levelers for acid copper electroplating. <i>Electrochimica Acta</i> , 2018, 273, 318-326.	5.2	55
33	A comparison of typical additives for copper electroplating based on theoretical computation. <i>Computational Materials Science</i> , 2018, 147, 95-102.	3.0	49
34	Enhancing inductance of spiral copper inductor with BaFe ₁₂ O ₁₉ /poly(phenylene oxide) composite as an embedded magnetic core. <i>Composites Part B: Engineering</i> , 2018, 138, 232-242.	12.0	13
35	Enhancing adhesion performance of no-flow prepreg to form multilayer structure of printed circuit boards with plasma-induced surface modification. <i>Surface and Coatings Technology</i> , 2018, 333, 24-31.	4.8	12
36	Preparation and Properties of Cyanate/Epoxy-based Composite with Thermal Conductive Silica Particles. <i>IOP Conference Series: Materials Science and Engineering</i> , 2018, 422, 012003.	0.6	0

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37	Electric and thermal performance of poly(phenylene oxide)-based composites with synergetic modification of carbon nanotubes and nanoplatelets. <i>Polymer Composites</i> , 2018, 39, E1920.	4.6	12
38	Investigation of poly (1-vinyl imidazole co 1, 4-butanediol diglycidyl ether) as a leveler for copper electroplating of through-hole. <i>Electrochimica Acta</i> , 2018, 283, 560-567.	5.2	49
39	Electrochemical Factors of Levelers on Plating Uniformity of Through-Holes: Simulation and Experiments. <i>Journal of the Electrochemical Society</i> , 2018, 165, E359-E365.	2.9	14
40	Direct activation of copper electroplating on conductive composite of polythiophene surface-coated with nickel nanoparticles. <i>Composites Part B: Engineering</i> , 2018, 154, 257-262.	12.0	18
41	Improving wettability of photo-resistive film surface with plasma surface modification for coplanar copper pillar plating of IC substrates. <i>Applied Surface Science</i> , 2017, 411, 82-90.	6.1	13
42	Preparation of rimose NiZnP electrode for hydrogen evolution reaction in alkaline medium by electroless and H ₂ SO ₄ etching. <i>Journal of Alloys and Compounds</i> , 2017, 719, 376-382.	5.5	8
43	Effects of surface-functionalized aluminum nitride on thermal, electrical, and mechanical behaviors of polyarylene ether nitrile-based composites. <i>Polymer Composites</i> , 2016, 37, 3033-3041.	4.6	12
44	Initiation electroless nickel plating by atomic hydrogen for PCB final finishing. <i>Chemical Engineering Journal</i> , 2016, 306, 117-123.	12.7	15
45	Copper coin-embedded printed circuit board for heat dissipation: manufacture, thermal simulation and reliability. <i>Circuit World</i> , 2015, 41, 55-60.	0.9	6
46	Characterization and application of aggregated porous copper oxide flakes for cupric source of copper electrodeposition. <i>Materials Letters</i> , 2015, 139, 458-461.	2.6	10
47	Properties and application of polyimide-based composites by blending surface functionalized boron nitride nanoplates. <i>Journal of Applied Polymer Science</i> , 2015, 132, .	2.6	28
48	Study on brown oxidation process with imidazole group, mercapto group and heterocyclic compounds in printed circuit board industry. <i>Journal of Adhesion Science and Technology</i> , 2015, 29, 1178-1189.	2.6	14
49	Improved Uniformity of Conformal Through-Hole Copper Electrodeposition by Revision of Plating Cell Configuration. <i>Journal of the Electrochemical Society</i> , 2015, 162, D575-D583.	2.9	21
50	Preparation and thermal effects of polyarylene ether nitrile aluminium nitride composites. <i>Polymer International</i> , 2014, 63, 546-551.	3.1	9
51	Plating Uniformity of Bottom-up Copper Pillars and Patterns for IC Substrates with Additive-assisted Electrodeposition. <i>Electrochimica Acta</i> , 2014, 120, 293-301.	5.2	77
52	A Catalytic and Interfacing PEDOT:PSS/CuPc Polymerized on Cloth Fiber to Electro-Metalize Stretchable Copper Conductive Pattern. <i>Advanced Materials Interfaces</i> , 0, , 2101462.	3.7	2